

# 600 V Switching Characteristics of GaN Polarization Super-Junction (PSJ) Transistors on Sapphire substrate

POWDEC K.K.,

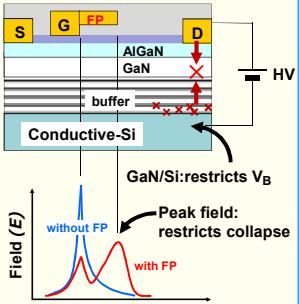
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## 【1. background】

### Issues for commercialization of GaN power transistors

Current collapse,  $R_{on}$  increase during operation, is still a big issue. Conventional technique of the Field-Plate, FP, plus conductive Si substrate is insufficient to cease the collapse and causes the low breakdown voltage,  $V_B$ . Therefore, a new principle is needed.

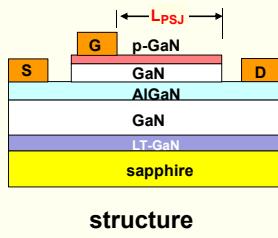


## 【2. Purpose】

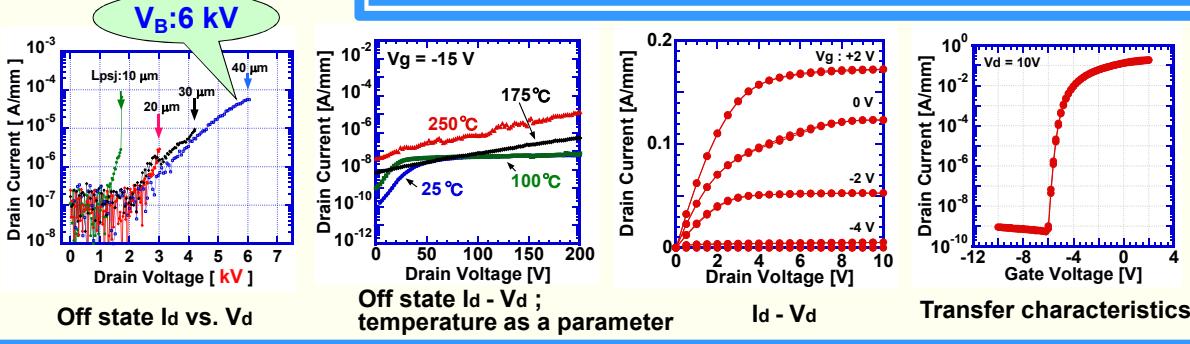
Propose the device principle and show the collapse-free switching at 600V of  $V_{dd}$  regime

## 【4. Transistor structure and DC characteristics】

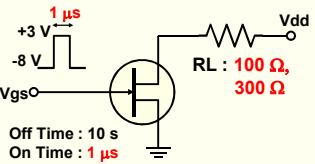
### PSJ-FET on sapphire sub.



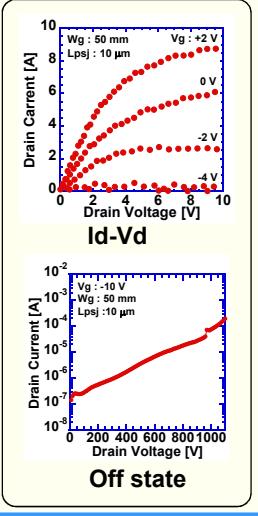
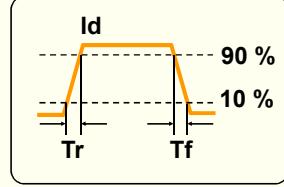
structure



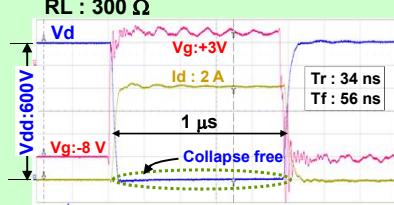
## 【5. Switching characteristics】



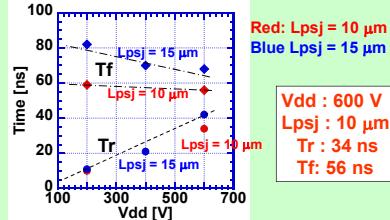
Test circuit



### Switching at $V_{dd} = 600V$

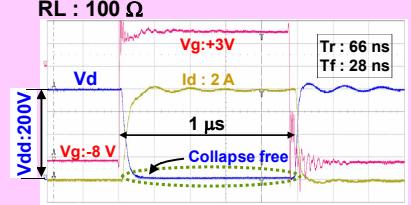


Switching waveform

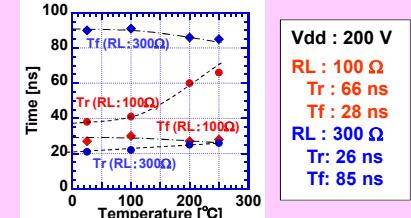


Vdd dependence of Tr and Tf

### Switching at 250 degC



Switching waveform



Temperature dependence of Tr and Tf

## 【6. Experimental results】

- Breakdown voltage,  $V_B$ , was proportional to  $L_{psj}$  and reached 6kV at  $L_{psj}=40mm$ ,
- The dynamic current collapse was not seen up to 600V of  $V_{dd}$ ,
- At 600V switching, rise-time,  $Tr$  and fall-time,  $Tf$  of the  $Id$  were 34nm and 56ns, respectively,
- At 250 degC, the collapse was not observed too.

## 【8. Conclusion】

- The polarization super-junction FET, PSJ-FET, perfectly suppressed the current collapse at 600V switching regime, in spite of the use of the insulating substrate.
- The system of PSJ device on sapphire has the potential of exploring over 600V switching regime where the conventional FP/Si system could never realized.

## 【7. Only one issue for using sapphire】

### Heat dissipation

Candidates:

- Sapphire removal
- Extreme thinning of sapphire
- Flip-chip
- Surface built-up block

材料	Heat resistance (W/mK)
Si	~ 140
GaN	~ 140
sapphire	~ 40

### Acknowledgement :

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